Fraunhofer IZM @ ECTC

IEEE ECTC 2015
in San Diego, CA

Tuesday, May 26, 2015
PROFESSIONAL DEVELOPMENT COURSES
Morning Courses 8:00 a.m. – Noon | Nautilus 5
Fundamentals of Electrical Design and Fabrication Processes of Interposers Including Their RDLs Course Leaders: Ivan Ndip and Michael Töpper | *Fraunhofer IZM*

Tuesday, May 26, 2015
PROFESSIONAL DEVELOPMENT COURSES
Afternoon Courses 1:15 p.m. – 5:15 p.m. | Harbor Island 2
Moisture and Media Influence on Microelectronic Package Reliability Course Leaders: Tanja Braun and Hans Walter | *Fraunhofer IZM*

Wednesday, May 27, 2015
PROGRAM SESSIONS: 1:30 P.M. – 5:10 P.M.
Session 9: Advancements in Substrate Technologie
A Sub-4 µm Via Technology of Thinfilm Polymers Using Scanning Laser Ablation Michael Töpper, Karin Hauck, Mario Schima, Danny Jaeger, and Klaus-Dieter Lang | *Fraunhofer IZM*

Wednesday, May 27, 2015
SESSION 38: INTERACTIVE PRESENTATIONS 2 | 2:00 P.M. - 4:00 P.M.
Committee: Interactive Presentations | Pavilion
Dependency of the Porosity and the Layer Thickness on the Reliability of Ag Sintered Joints During Active Power Cycling Constanze Weber, Matthias Hutter, and Stefan Schmitz | *Fraunhofer IZM* Klaus-Dieter Lang | *Technical University Berlin*

Thursday, May 28, 2015
PROGRAM SESSIONS: 8:00 A.M. - 11:40 A.M.
Session 18: Advanced Optical Interconnects
Thin Glass Based Electro-Optical Circuit Board (EOCB) with Through Glass Vias, Gradient-Index Multimode Optical Waveguides and Collimated Beam Mid-Board Coupling Interfaces Lars Brusberg, Henning Schröder, and Dominik Pernthaler | *Fraunhofer IZM* Christian Ranzinger | *Contag AG*; Marco Queisser, Christian Herbst, Sebastian Marx, Jens Hofmann, Marcel Neitz, and Klaus-Dieter Lang | *Technical University Berlin*

Friday, May 29, 2015
PROGRAM SESSIONS 8:00 A.M. - 11:40 A.M
Session 25: Fan-Out and Wafer Level Packaging
Large Area Compression Molding for Fan-Out Panel Level Packaging Tanja Braun, Stefan Raatz, Volker Bader, Jörg Bauer, Karl-Friedrich Becker, and Rolf Aschenbrenner | *Fraunhofer IZM* Steve Voges, Ruben Kahle, Tina Thomas, and Klaus-Dieter Lang | *Technical University Berlin*

Friday, May 29, 2015
PROGRAM SESSIONS: 1:30 P.M. - 5:10 P.M.
Session 31: MEMS and Sensors
Application of TSV Integration and Wafer Bonding Technologies for Hermetic Wafer Level Packaging of MEMS Components for Miniaturized Timing Devices K. Zoschke, C.-A. Manier, M. Wilke, and H. Oppermann | *Fraunhofer IZM*; D. Ruffieux | *CSEM*; J. Dekker and A. Jaakkola | *VTT Technical Research Centre of Finland*; S. Dalla Piazza | *Micro Crystal AG*; G. Allegato | *STMicroelectronics*; K.-D. Lang | *Technical University of Berlin*

2014 ECTC BEST PAPER AWARDS
OUTSTANDING INTERACTIVE PRESENTATION
CO2 – Laser Drilling of TGVs for Glass Interposer Applications Lars Brusberg and Henning Schröder | *Fraunhofer IZM* Marco Queisser, Marcel Neitz, and Klaus-Dieter Lang | *Technical University Berlin*